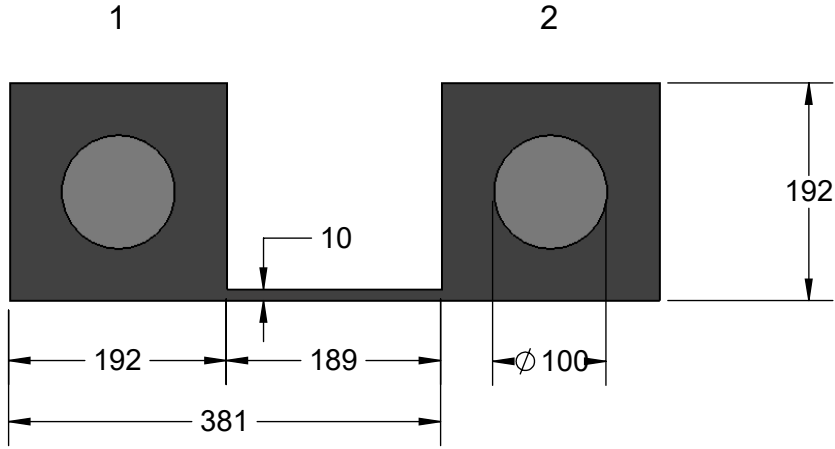


BONDING PAD

DETAIL 1
CODE G



PITCH X 381 μ m
PITCH Y 508 μ m

REFERENCE:

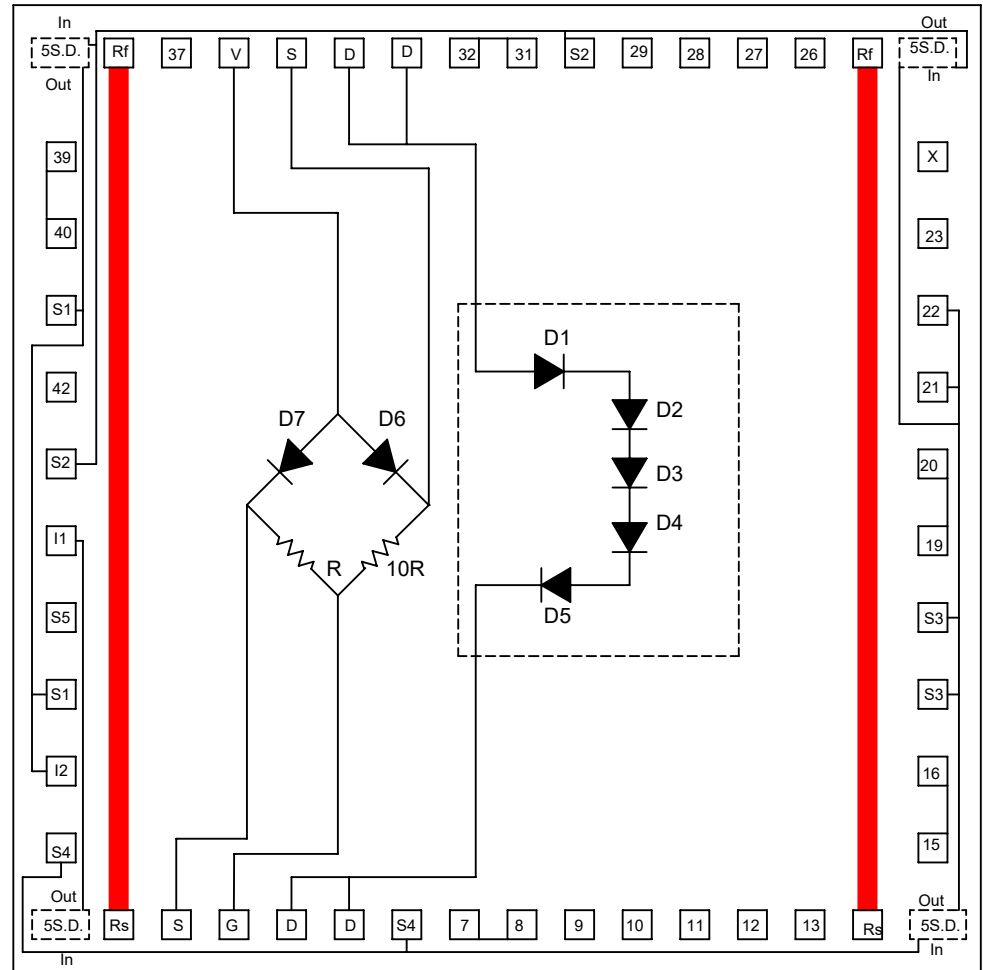
- Rf~Rs = HEATER Si RESISTIVE
- D = DIODE
- V = +VOLTAGE
- G = GROUND
- S = TEMPERATURE SENSE

NOTES:

- 1) DIMENSIONS IN MICRONS (μ m) OR AS SPECIFIED.
- 2) THICKNESS: 635 μ m (OTHER AVAILABLE).
- 3) PASSIVATION: NITRIDE 10KA THICKNESS (1.0 μ m).
- 4) PACKAGING: STANDARD WAFFLE PACK (TRAY).
- 5) PAD METAL THICKNESS: 17KA (1.7 μ m).
- 6) SILICON ORIENTATION 1-1-1.
- 7) SILICON TYPE P.

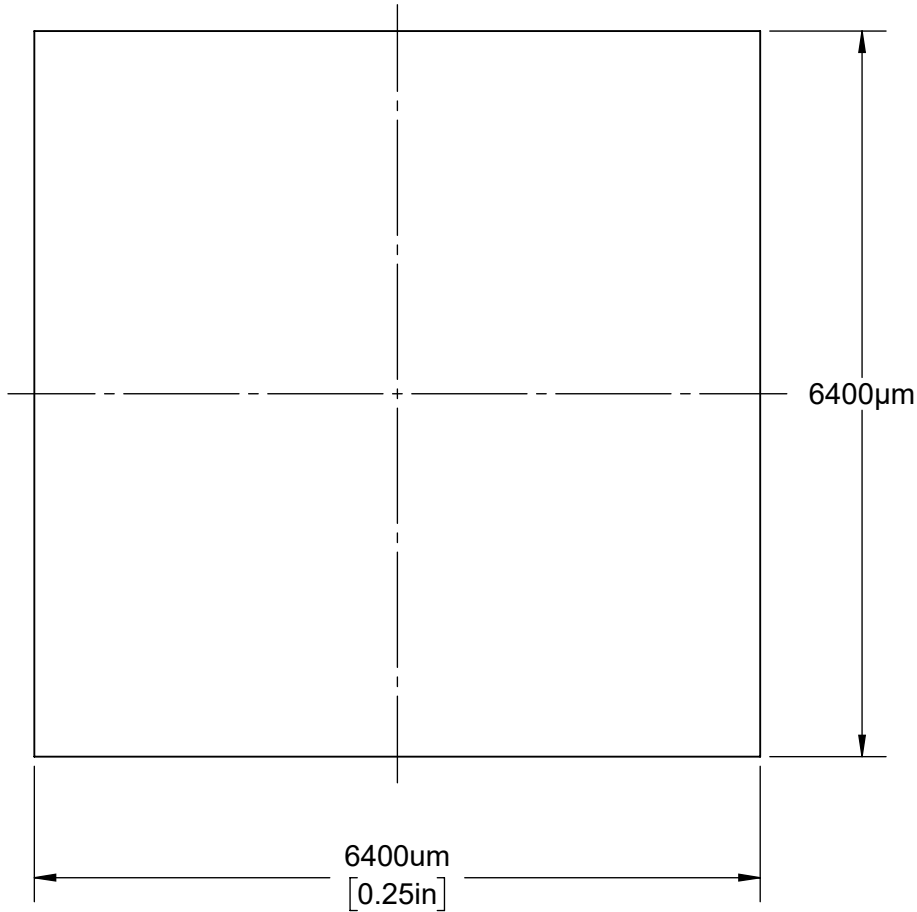
PART NUMBER TABLE				
PART NUMBER	DIE SIZE	DIE PER WAFER	BOND PAD	DETAIL
PST4-G6.35A	6.35mm	~236	ϕ 100 μ m	1

PST4 THERMAL DIE 6.35mm x 6.35mm

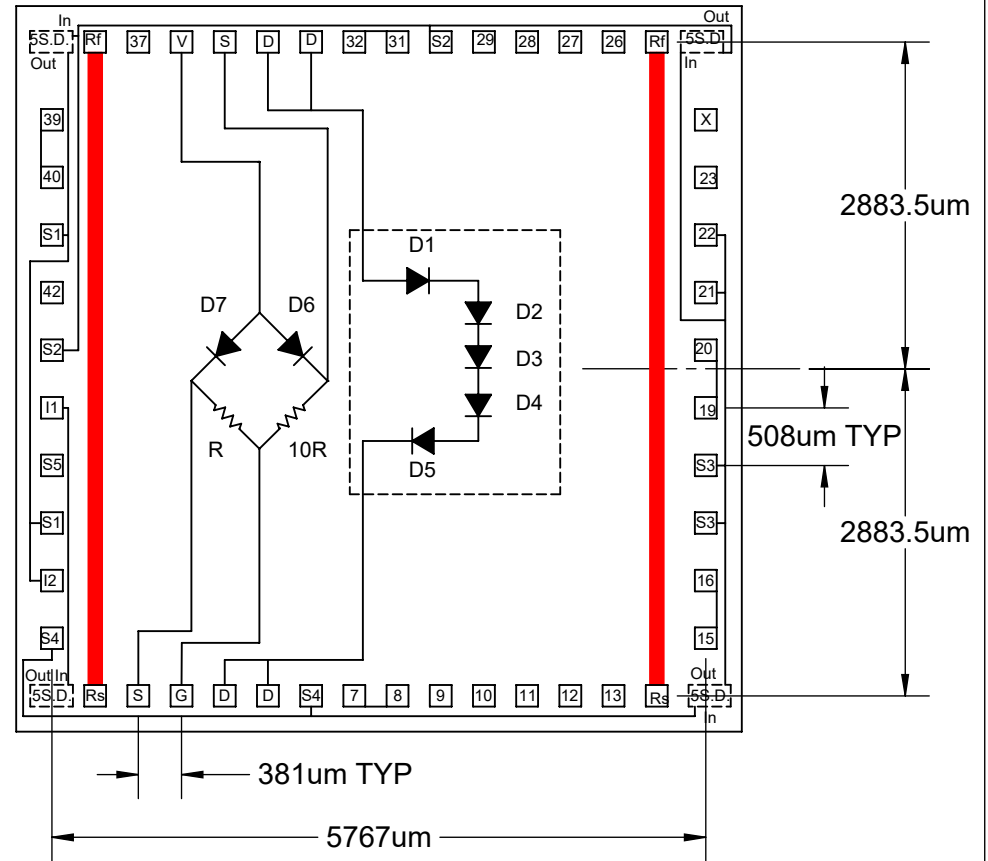


APPROVALS	DATE	TopLine®			
DRAWN T. Au	7/22/2018				
ENG M. Hart	7/22/2018	TITLE PST4 THERMAL DIE 6.35mm x 6.35mm			
MFG		SCALE 20:1	SIZE A	DRAWING NO. 140021	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BACK SIDE



PAD SIDE



REFERENCE:
 Rf~Rs = HEATER Si RESISTIVE
 D = DIODE
 V = +VOLTAGE
 G = GROUND
 S = TEMPERATURE SENSE

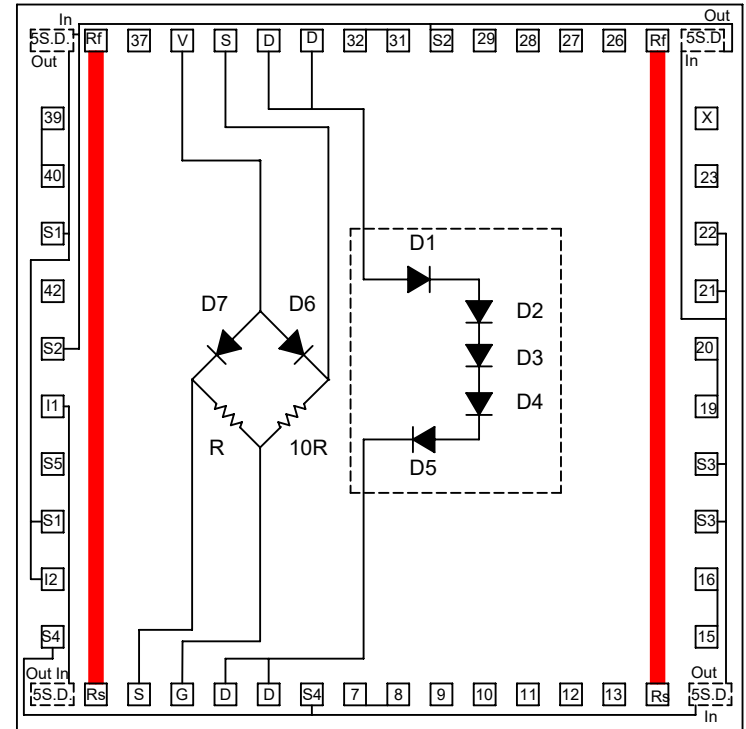
TopLine®			
TITLE		PST4 THERMAL DIE 6.35mm x 6.35mm	
SCALE	SIZE	DRAWING NO.	REV
40:1	A	140021	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

NET LIST

(0,0) is located at the center of the die

MICRON um				MICRON um			
PIN#	NAME	X	Y	PIN#	NAME	X	Y
1	Rs (1)	-2502.5	-2883.5	25	Rf (1)	2450.5	2883.5
2	S (1)	-2121.5	-2883.5	26	Pin 26	2069.5	2883.5
3	G	-1740.5	-2883.5	27	Pin 27	1688.5	2883.5
4	D (1)	-1359.5	-2883.5	28	Pin 28	1307.5	2883.5
5	D (2)	-978.5	-2883.5	29	Pin 29	926.5	2883.5
6	S4 (1)	-597.5	-2883.5	30	S2 (1)	545.5	2883.5
7	Pin 7	-216.5	-2883.5	31	Pin 31	164.5	2883.5
8	Pin 8	164.5	-2883.5	32	Pin 32	-216.5	2883.5
9	Pin 9	545.5	-2883.5	33	D (3)	-597.5	2883.5
10	Pin 10	926.5	-2883.5	34	D (4)	-978.5	2883.5
11	Pin 11	1307.5	-2883.5	35	S (2)	-1359.5	2883.5
12	Pin 12	1688.5	-2883.5	36	V	-1740.5	2883.5
13	Pin 13	2069.5	-2883.5	37	Pin 37	-2121.5	2883.5
14	Rs (2)	2450.5	-2883.5	38	Rf (2)	-2502.5	2883.5
15	Pin 15	2883.5	-2375.5	39	Pin 39	-2883.5	2196.5
16	Pin 16	2883.5	-1867.5	40	Pin 40	-2883.5	1688.5
17	S3 (1)	2883.5	-1359.5	41	S1 (1)	-2883.5	1180.5
18	S3 (2)	2883.5	-851.5	42	Pin 42	-2883.5	672.5
19	Pin 19	2883.5	-343.5	43	S2 (2)	-2883.5	164.5
20	Pin 20	2883.5	164.5	44	I1	-2883.5	-343.5
21	Pin 21	2883.5	672.5	45	S5	-2883.5	-851.5
22	Pin 22	2883.5	1180.5	46	S1 (2)	-2883.5	-1359.5
23	Pin 23	2883.5	1688.5	47	I2	-2883.5	-1867.5

NC = NO CONNECTION



REFERENCE:
 Rf~Rs = HEATER Si RESISTIVE ELEMENTS
 D = DIODE
 V = +VOLTAGE
 G = GROUND
 S = TEMPERATURE SENSE

TopLine®			
TITLE PST4 THERMAL DIE 6.35mm x 6.35mm			
SCALE 40:1	SIZE A	DRAWING NO. 140021	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 4

PART NUMBERING SYSTEM

PST

-

4

G

-

6.3

A

-

BG200

-

W

DIE/WAFER

PST = SINGLE DIE
PSTW = UNSAWN WAFER
5" (125mm)

SERIES

4 = 6.35mm

PAD

G = ϕ 100 μ m

DIE SIZE

<u>CODE</u>	<u>MM</u>	<u>MIL</u>
6.3	6.35	250

PAD MATERIAL

A = Al98, Si1.0, Cu1.0

OPTIONS

DIE THINNING

<u>CODE</u>	<u>MM</u>	<u>MIL</u>
NONE	635 μ M	0.025"
BG530	530 μ M	0.021"
BG430	430 μ M	0.017"
BG360	360 μ M	0.014"
BG250	250 μ M	0.010"
BG200	200 μ M	0.008"
BG150	150 μ M	0.006"
BG100	100 μ M	0.004"

PACKAGING

<u>SIZE</u>	<u>TRAY</u>	<u>QTY</u>
6.3mm	2-INCH	25 PCS

TopLine[®]

TITLE PST4 THERMAL DIE
6.35mm x 6.35mm

SCALE	SIZE	DRAWING NO.	REV
NONE	A	140021	A

DO NOT SCALE DRAWING

SHEET 4 OF 4